

# MCT6, MCT61, MCT62 Dual Phototransistor Optocouplers

## Features

- Two isolated channels per package
- Two packages fit into a 16 lead DIP socket
- Choice of three current transfer ratios
- Underwriters Laboratory (U.L.) recognized File E90700

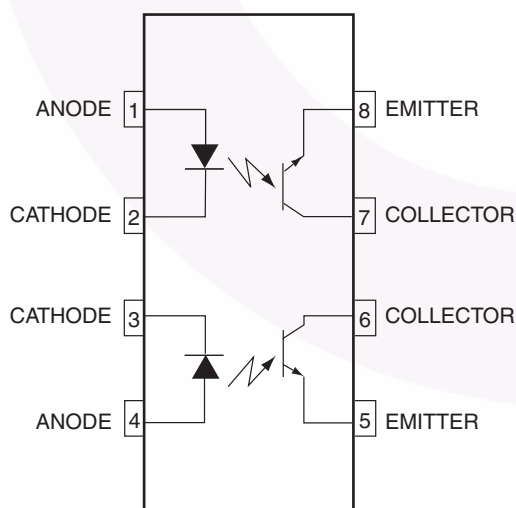
## Applications

- AC line/digital logic – isolate high voltage transients
- Digital logic/digital logic – eliminate spurious grounds
- Digital logic/AC triac control – isolate high voltage transients
- Twisted pair line receiver – eliminate ground loop feedthrough
- Telephone/telegraph line receiver – isolate high voltage transients
- High frequency power supply feedback control – maintain floating grounds and transients
- Relay contact monitor – isolate floating grounds and transients
- Power supply monitor – isolate transients

## Description

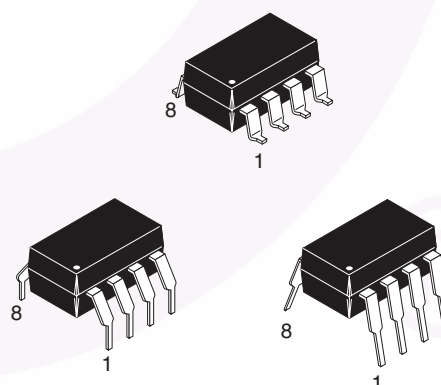
The MCT6X Optocouplers have two channels for density applications. For four channel applications, two-packages fit into a standard 16-pin DIP socket. Each channel is an NPN silicon planar phototransistor optically coupled to a gallium arsenide infrared emitting diode.

## Schematic



Equivalent Circuit

## Package Outlines



## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Rating	Value	Unit
TOTAL DEVICE			
T <sub>STG</sub>	Storage Temperature	-55 to +150	°C
T <sub>OPR</sub>	Operating Temperature	-55 to +100	°C
T <sub>SOL</sub>	Lead Solder Temperature (wave solder)	250 for 10 sec	°C
P <sub>D</sub>	Total Device Power Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	400	mW
		5.33	mW/°C
EMITTER (Each channel)			
I <sub>F</sub>	Forward Current – Continuous	60	mA
I <sub>F(pk)</sub>	Forward Current – Peak (PW = 1μs, 300pps)	3	A
V <sub>R</sub>	Reverse Voltage	3.0	V
P <sub>D</sub>	LED Power Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C (Total Input)	100	mW
		1.3	mW/°C
DETECTOR (Each channel)			
I <sub>C</sub>	Collector Current – Continuous	30	mA
P <sub>D</sub>	Detector Power Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	150	mW
		2.0	mW/°C

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise specified)**Individual Component Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.*	Max.	Units
<b>EMITTER</b>						
$V_F$	Input Forward Voltage	$I_F = 20\text{mA}$		1.2	1.5	V
$V_R$	Reverse Voltage	$I_R = 10\mu\text{A}$	3.0	25		V
$I_R$	Reverse Current	$V_R = 5\text{V}$		0.001	10	$\mu\text{A}$
$C_J$	Junction Capacitance	$V_F = 0\text{V}$ , $f = 1\text{MHz}$		50		pF
<b>DETECTOR</b>						
$BV_{CEO}$	Collector-Emitter Breakdown Voltage	$I_C = 1.0\text{mA}$ , $I_F = 0$	30	85		V
$BV_{ECO}$	Emitter-Collector Breakdown Voltage	$I_E = 100\mu\text{A}$ , $I_F = 0$	6	13		V
$I_{CEO}$	Collector-Emitter Dark Current	$V_{CE} = 10\text{V}$ , $I_F = 0$		5	100	nA
$C_{CE}$	Capacitance	$V_{CE} = 0\text{V}$ , $f = 1\text{MHz}$		8		pF

**Transfer Characteristics**

Symbol	Characteristic	Test Conditions	Min.	Typ.*	Max.	Units
SWITCHING CHARACTERISTICS (AC)						
t <sub>on</sub>	Non-Saturated Turn-on Time	R <sub>L</sub> = 100Ω, I <sub>C</sub> = 2mA, V <sub>CC</sub> = 10V		2.4		μs
t <sub>off</sub>	Non-Saturated Turn-off Time			2.4		μs
CURRENT TRANSFER RATIO, COLLECTOR-EMITTER (DC)						
CTR	MCT6	I <sub>F</sub> = 10mA, V <sub>CE</sub> = 10V	20			%
	MCT61	I <sub>F</sub> = 5mA, V <sub>CE</sub> = 5V	50			
	MCT62		100			
V <sub>CE(sat)</sub>	Saturation Voltage	I <sub>F</sub> = 16mA, I <sub>C</sub> = 2mA		0.15	0.40	V

**Isolation Characteristics**

Symbol	Characteristic	Test Conditions	Min.	Typ.*	Max.	Units
$V_{ISO}$	Input-Output Isolation Voltage	$I_{I-O} \leq 10\mu\text{A}$ , $t = 1\text{min.}$	5000			Vac(rms)
$R_{ISO}$	Isolation Resistance	$V_{I-O} = 500\text{VDC}$	$10^{11}$			$\Omega$
$C_{ISO}$	Isolation Capacitance	$f = 1\text{MHz}$		0.5		pF

\*All typicals at  $T_A = 25^\circ\text{C}$

## Typical Performance Curves

Fig. 1 Normalized CTR vs. Forward Current

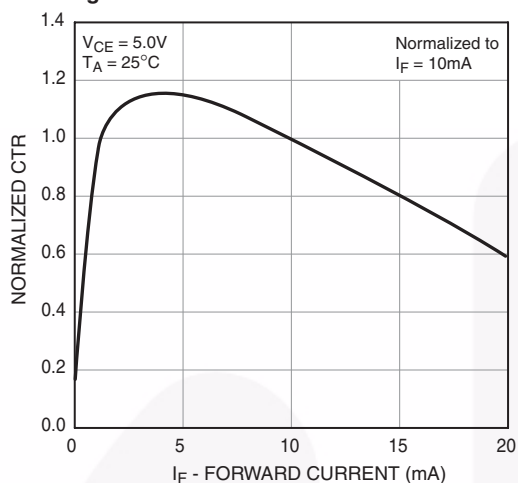


Fig. 2 Normalized CTR vs. Ambient Temperature

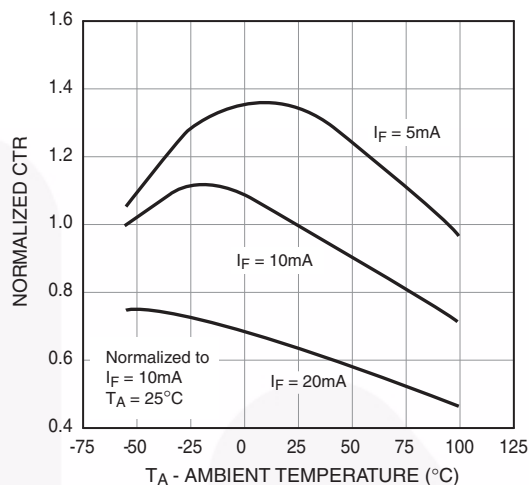


Fig. 3 Dark Current vs. Ambient Temperature

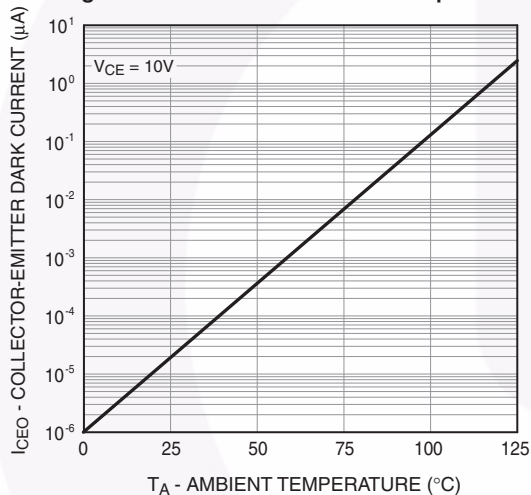


Fig. 4 Switching Speed vs. Load Resistor

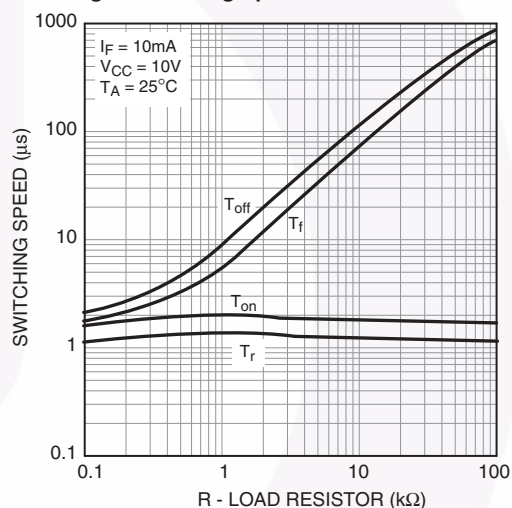


Fig. 5 LED Forward Voltage vs. Forward Current

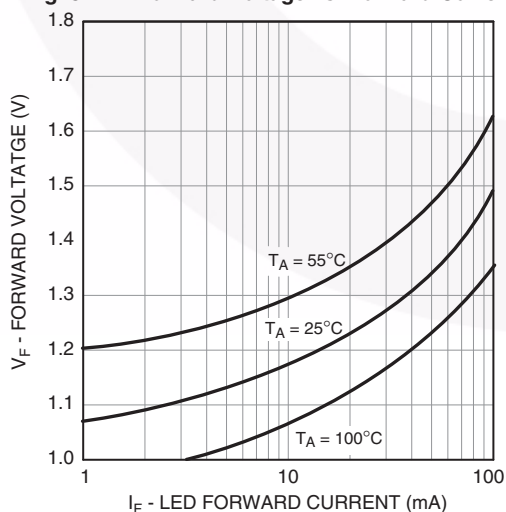
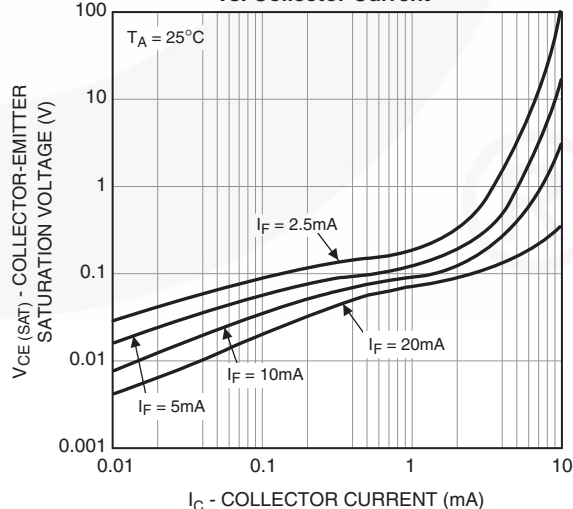
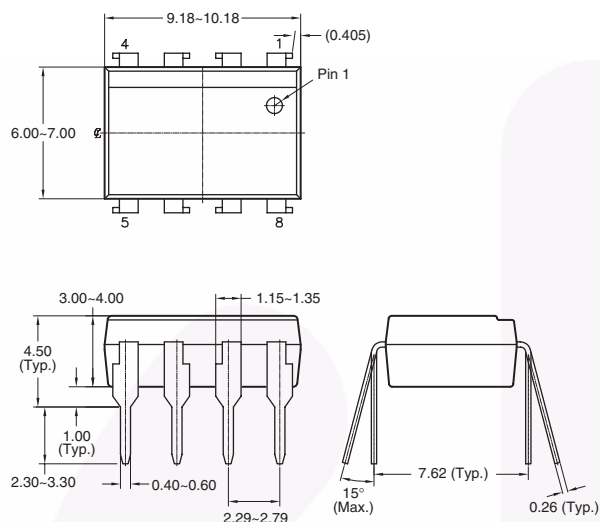


Fig. 6 Collector-Emitter Saturation Voltage vs. Collector Current

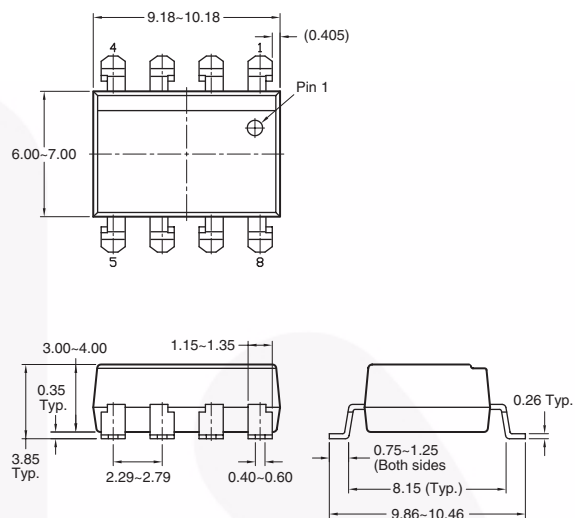


## Package Dimensions

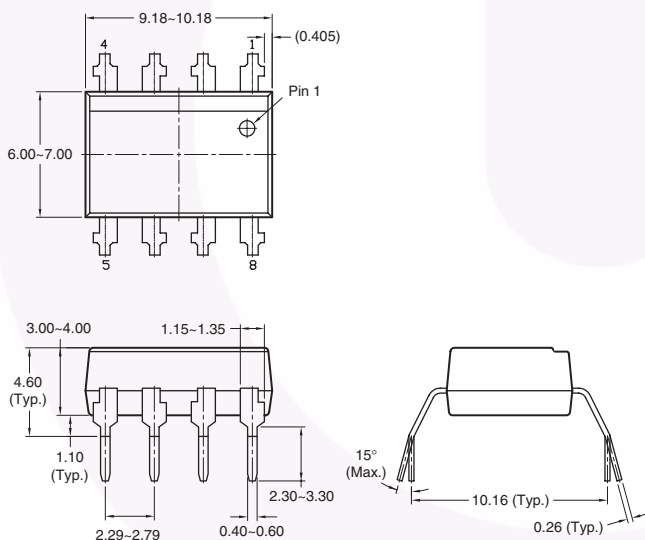
### Through Hole



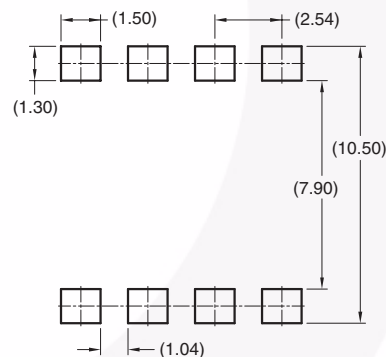
### Surface Mount



### 0.4" Lead Spacing



### Recommend Pad Layout for Surface Mount Leadform



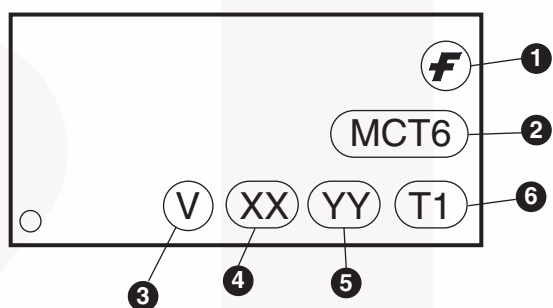
### Note:

All dimensions are in millimeters.

## Ordering Information

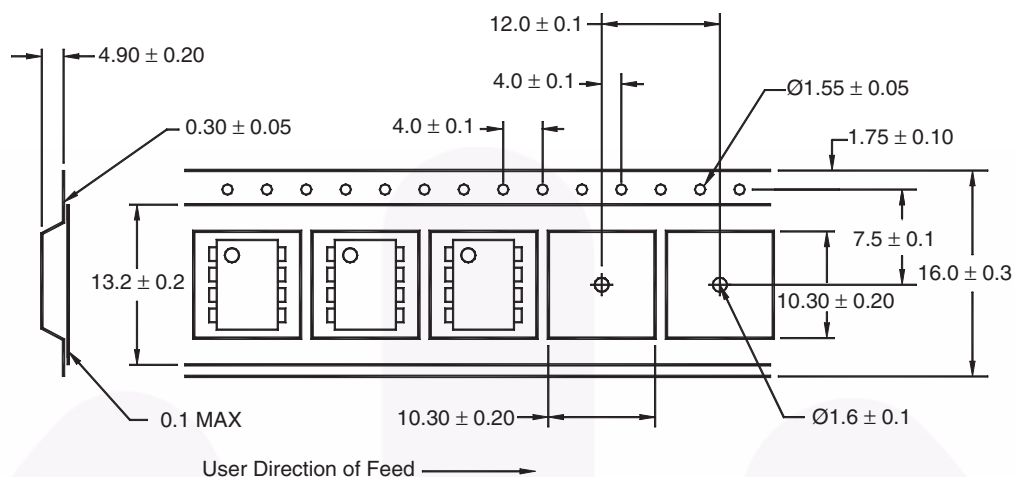
Option	Example Part Number	Description
No Option	MTC6	Standard Through Hole
S	MTC6S	Surface Mount Lead Bend
SD	MTC6SD	Surface Mount; Tape and Reel
W	MTC6W	0.4" Lead Spacing

## Marking Information



Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	Two digit year code, e.g., '03'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

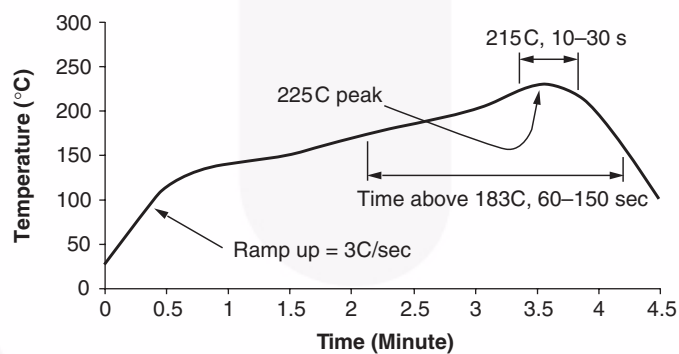
## Carrier Tape Specifications



### Note:

All dimensions are in inches (millimeters)

## Reflow Profile





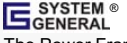


- Peak reflow temperature: 225C (package surface temperature)
- Time of temperature higher than 183C for 60-150 seconds
- One time soldering reflow is recommended



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